PCN Number:	20180305000	**PCN Date:**	Mar 29, 2018
Title:	Qualification of CFAB wafer fab site for select devices in LBC5 process technology		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	June 29, 2018	**Estimated Sample Availability:**	Date provided at sample request.

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

This change notification is to announce the qualification of CFAB as an additional wafer fab site option for the LBC5 devices listed in the product affected section of this document.

Current			**Additional**		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
DP1DM5	LBC5	200 mm	CFAB	LBC5	200 mm

The LBC5 process technology has been running successfully in production at CFAB since 2012.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Sites	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas

New

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
CFAB	**CU3**	**CHN**	Chengdu

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

DRV8313RHH	DRV8313RHH

Qualification Report

CFAB OFFLOAD FROM DMOS5 – Moobot (DRV8803PWPR)

Approve Date 12-Nov-2015

Product Attributes

Die Attributes	Qual Device: C8803A0A	QBS Product Reference: DRV8803PWP	QBS Product Reference: DRV8804DW-P	QBS Process Reference: TAS5613APHD	QBS Package Reference: BUF11704AIPWPR	QBS Package Reference: TPA1517DWP	QBS Package Reference: TPS40057PWP	QBS Package Reference: TPS65161PWP
Assembly Site	TITL	TI TAIWAN	MLA (TIM)	TAI (TITL)	TAI	TAI	TAI	TAI
Package Family	HTSSOP	HTSSOP	SOIC - DW	HTQFP	TSSOP	SOIC	TSSOP	TSSOP
Wafer Fab Supplier	CFAB	DM5	DM5	CFAB	DMOS5	SFAB	DFAB	DFAB
Wafer Process	LBC5	LBC-5X	LBC5	LBC5	50HPA07	Bipolar	LBC4	LBC4x

- QBS: Qual By Similarity
- Qual Device C8803A0A is qualified at LEVEL3-260CG

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: C8803A0A	QBS Product Reference: DRV8803PWP	QBS Product Reference: DRV8804DW-P	QBS Process Reference: TAS5613APHD	QBS Package Reference: BUF11704AIPWPR	QBS Package Reference: TPA1517DWP	QBS Package Reference: TPS40057PWP	QBS Package Reference: TPS65161PWP
AC	Autoclave 121C	96 Hours	-	-	-	3/231/0	1/77/0	3/231/0	1/77/0	1/77/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	-	Pass	Pass	-	-	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0	-	3/78/0	-	-
HBM	ESD - HBM	3000 V	-	-	1/3/0	-	-	-	-	-
CDM	ESD - CDM	1500 V	-	1/3/0	1/3/0	-	-	-	-	-
HTOL	Life Test, 125C	1000 Hours	-	-	-	-	-	3/120/0	-	-
HTOL	Life Test, 155C	240 Hours	-	-	-	3/231/0	-	-	-	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	-	3/230/0	1/77/0	3/231/0	1/77/0	1/77/0
LU	Latch-up	(per JESD78)	-	-	1/6/0	3/18/0	-	-	-	-
SBS	Ball Shear	Wires	-	-	-	-	1/76/0	-	-	-
TC	Temperature Cycle -65C/150C	500 Cycles	-	2/154/0	3/231/0	3/231/0	1/77/0	3/231/0	1/77/0	1/77/0
TS	Thermal Shock, -65/150C	500 Cycles	-	-	-	-	1/77/0	3/231/0	1/77/0	1/77/0
WBP	Bond Pull	Wires	-	-	-	-	1/76/0	3/228/0	-	-
WBS	Bond Shear	Wires	-	-	-	-	-	3/228/0	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:
Qualified Pb-Free (SMT) and Green

Qualification Report

CFAB OFFLOAD from DMOS5 (DRV8844PWPR)

Approve Date 12-Nov-2015

Product Attributes

Die Attributes	Qual Device: C8844A1	QBS Product Reference: DRV8844PWP	QBS Process Reference: TAS5613APHD	QBS Package Reference: BUF11704AIPWPR	QBS Package Reference: TPA1517DWP	QBS Package Reference: TPS40057PWP	QBS Package Reference: TPS65161PWP
Assembly Site	TITL	TAI	TAI (TITL)	TAI	TAI	TAI	TAI
Package Family	HTSSOP	-	HTQFP	TSSOP	SOIC	TSSOP	TSSOP
Wafer Fab Supplier	CFAB	DM0S5	CFAB	DMOS5	SFAB	DFAB	DFAB
Wafer Process	LBC5	LBC5X	LBC5	50HPA07	Bipolar	LBC4	LBC4x

- QBS: Qual by Similarity
- Qual Device C8844A1 is qualified at LEVEL3-260CG

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: C8844A1	QBS Product Reference: DRV8844PWP	QBS Process Reference: TAS5613APHD	QBS Package Reference: BUF11704AIPWPR	QBS Package Reference: TPA1517DWP	QBS Package Reference: TPS40057PWP	QBS Package Reference: TPS65161PWP
AC	Autoclave 121C	96 Hours	-	-	3/231/0	1/77/0	3/231/0	1/77/0	1/77/0
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	1/30/0	-	-	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-	3/78/0	-	-
HBM	ESD - HBM	3000 V	-	1/3/0	-	-	-	-	-
CDM	ESD - CDM	1500 V	-	1/3/0	-	-	-	-	-
HTOL	Life Test, 125C	1000 Hours	-	-	-	-	3/120/0	-	-
HTOL	Life Test, 155C	240 Hours	-	-	3/231/0	-	-	-	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	3/230/0	1/77/0	3/231/0	1/77/0	1/77/0
LU	Latch-up	(per JESD78)	-	2/12/0	3/18/0	-	-	-	-
SBS	Ball Shear	Wires	-	-	-	1/76/0	-	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	1/77/0	3/231/0	1/77/0	3/231/0	1/77/0	1/77/0
TS	Thermal Shock, -65/150C	500 Cycles	-	-	-	1/77/0	3/231/0	1/77/0	1/77/0
WBP	Bond Pull	Wires	-	-	-	1/76/0	3/228/0	-	-
WBS	Bond Shear	Wires	-	-	-	-	3/228/0	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:
Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com